

MLU-808 CS /FS

Micro-Laser Soldering System

The Micro-Laser Soldering System improves quality and production. It is easy to operate with many laser beam special features.

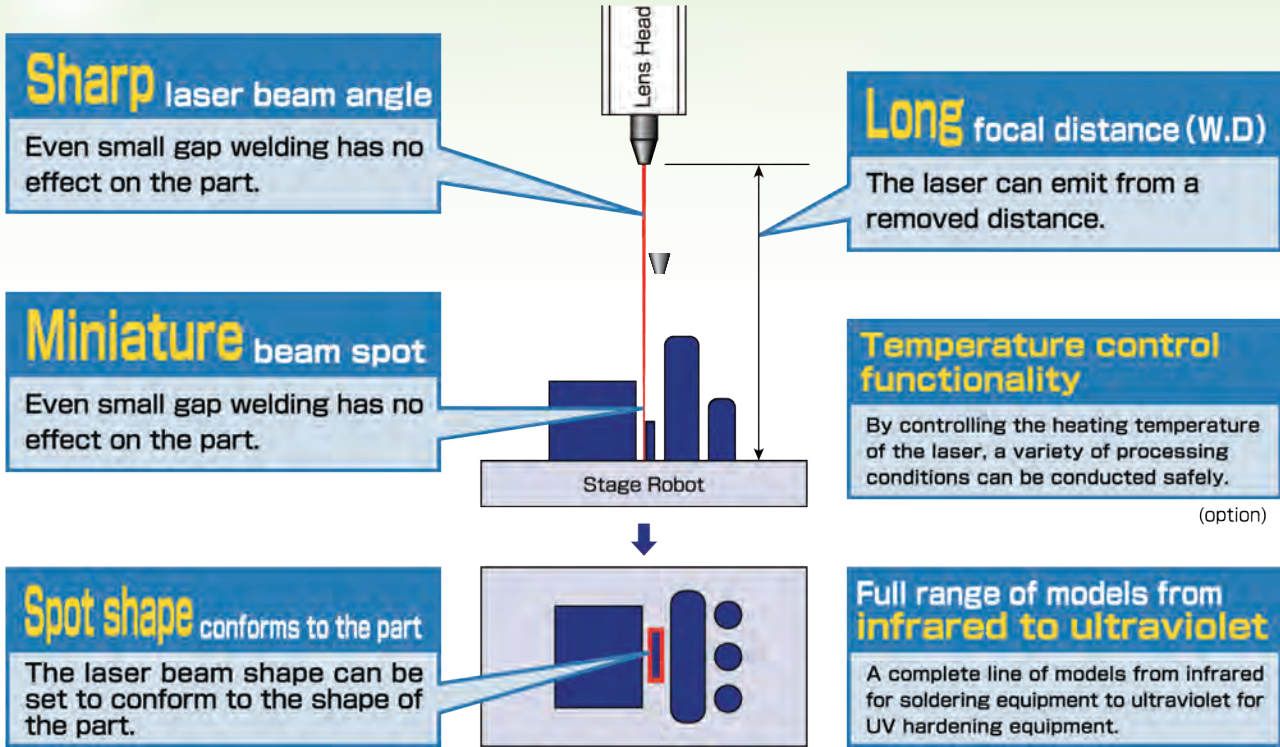
The **MLU-808 CS** is a high specification micro-laser system best suited for soldering on micro or narrow pitch components.

The **MLU-808 FS** is a micro-laser soldering system with a laser head reduced in size and weight. The small head allows incorporation with all types of robots and equipment.



Micro-Laser Soldering System

The 6 special features of the Micro-Laser System. Through optical technology, it is possible to simultaneously produce miniature beam spot.



Examples of a variety of application soldering

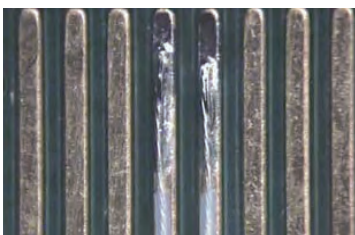
Chip Coating (0606)



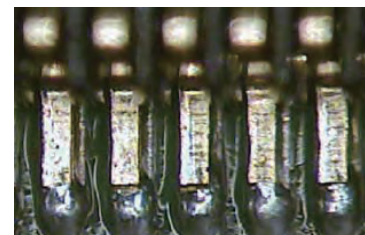
Through hole and pin



Cable pattern (width 100nm)



Terminal pattern



MLU-80 CS/FS Specifications

Unit Model	MLU-808CS	MLU-808FS
Laser Unit		
Material	Semiconductor Laser	
Wavelength	808 nm (OP 940 nm 980 nm)	
Laser Output	35 W	30 W 45 W (OP 60W)
Power	Single phase AC100V 50/60Hz	
Head Dimensions	172 (W) x 124 (D) x 280 (H) mm	78 (W) x 43 (D) x 173 (H) mm
Laser Oscillator Dimensions		240 (W) x 208 (D) x 244 (H) mm
Power Source Dimensions	430 (W) x 350 (D) x 150 (H) mm	430 (W) x 350 (D) x 150 (H) mm
Head Weight	3.5 kg	0.5 kg
Laser Oscillator Weight		4 kg
Power Source Weight	15 kg	15 kg
Working Distance and Beam Diameter		
35 mm	40 nm	200 nm
55 mm	60 nm	300 nm
75 mm	80 nm	400 nm
95 mm	100 nm	500 nm
*** Working distance and beam diameter may vary depending upon specifications		
Automatic Stage Robot Unit		
Movement Range	X-axis 300 mm y-axis 320 mm z-axis 100 mm	
Repetitive Positioning	0.02 m/m	
Main Body Weight	35 kg	
External Dimensions	560 mm (W) x 529 mm (D) x 649 mm (H)	
Electric Power	Single phase AC100V	